

CUSTOMER-DRIVEN FOUNDRY SOLUTIONS

UMC

DEAR CUSTOMERS

With the rising performance and shrinking feature sizes of our leading-edge production technologies, UMC's customers today enjoy unprecedented opportunities to develop the wide variety of chips needed to power the global economy. At the same time, these new technologies alone are no longer sufficient to satisfy the broad range of needs in today's digital economy. UMC is sharply focused

on developing tailored solutions that enable customers to leverage the inherent benefits of the full range of our advanced technologies. UMC's focus on delivering customer-driven foundry solutions is an essential element in meeting our goal to deliver the world's best technologies, support and manufacturing to our foundry customers.

Stan Hung
Stan Hung, Chairman

Shih-Wei Sun
Shih-Wei Sun, CEO



Left: Chairman Stan Hung; Right: CEO Shih-Wei Sun

UMC PROFILE

Full Company Name	United Microelectronics Corporation
Founded	1980
Headquarters	No. 3, Li-Hsin 2nd Rd., Hsinchu Science Park, Hsinchu, Taiwan, R.O.C.
Global Locations	Fabs: Japan, Taiwan, Singapore Offices: Europe, Japan, Singapore, Taiwan, U.S.
Number of Employees	Over 13,000 Worldwide
Core Competencies	Pure-play foundry with internal R&D capability, world-class 200/300mm manufacturing, solid engineering base, and leading-edge process technology
Technology	CMOS Logic from 0.45um to 28nm, HV, RF, Mixed Signal, CIS, eNVM
Chairman	Stan Hung
CEO	Dr. Shih-Wei Sun
Stock Listing	NYSE: UMC, TWSE: 2303

UMC is a leading global semiconductor foundry that provides advanced technology and manufacturing services for applications spanning every major sector of the IC industry. Founded in 1980 as Taiwan's first semiconductor company, UMC is a foundry technology leader. UMC's customer-driven foundry solutions enable chip designers to leverage the strength of the company's leading-edge processes, which include 28nm, mixed signal/RFCMOS, and a wide range of specialty technologies. The company employs over 13,000 people worldwide and has an extensive network of service offices in Taiwan, Japan, Singapore, Europe, and the United States to meet the needs of its global clientele.

Leading-Edge Foundry Technologies

As a global industry pioneer, UMC was the first foundry to ship wafers using copper materials, to produce chips on 300mm wafers, to deliver functional 65nm ICs to its customers, and to produce chips using 28nm process technology. UMC's leading-edge foundry technologies enable the creation of faster and more powerful chips to meet today's demanding applications, including high-k/metal gate, low-k dielectrics, immersion lithography, and mixed signal/RFCMOS.

The Industry Leader

UMC led the development of the commercial semiconductor industry in Taiwan. It was the first local company to offer foundry services, as well as the first semiconductor company to list on the Taiwan Stock Exchange (1985). UMC is responsible for many local industry innovations, including the introduction of the employee share bonus system, often credited as a primary factor in the development of a prominent electronics industry in Taiwan. UMC also enables customers to access supply chain information online through the MyUMC online portal, an industry first when it was introduced in 1998.

Customer-Driven Foundry Solutions

UMC is committed to the timely delivery of leading-edge solutions that serve the specific and unique requirements of our customers in the face of today's advanced applications. UMC collaborates closely with customers as well as partners throughout the entire supply chain, including equipment, EDA tool, and IP vendors, to work synergistically towards each customer's SoC silicon success. The result is a greater chance of first pass silicon success for today's SoC designs.

UMC's customer-driven foundry solutions start from a common logic-based platform, where designers can choose the process technology and transistor options that best fit their application. From there, technologies such as RFCMOS and embedded Flash can be used to further fine-tune the process for customers' individual needs. Furthermore, as IP has become a critical resource for today's SoCs, we have worked to provide basic design building blocks as well as more complex IP that are optimized for portability and cost, developed both internally and from third-party partners.

With advanced technology, a broad IP portfolio, system knowledge, and advanced 300mm manufacturing, UMC offers comprehensive solutions that help customers deliver successful results in a timely fashion.

World-Class Manufacturing

UMC is a 300mm manufacturing leader with two advanced 300mm fabs in operation. Fab 12A in Tainan, Taiwan has been in volume production for customer products since 2002 and is currently manufacturing the industry's most advanced 28nm products. UMC's second 300mm fab, Fab 12i, is located in Singapore's Pasir Ris Wafer Park. This second-generation 300mm facility is also in volume production. The advanced automation, mature defect density, and competitive cycle times along with a customer-driven capacity expansion plan enable UMC to be the foundry of choice for customers' manufacturing needs. In addition the company has seven 8-inch fabs and one 6-inch fab that manufacture products targeting every major sector of the semiconductor industry.

Numerous Industry Affiliations

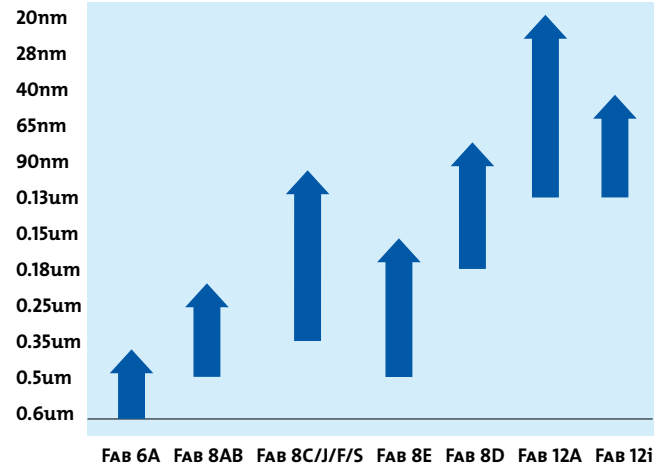
UMC is a founding member of the GSA (Global Semiconductor Association) and participates in the PFI (Power Forward Initiative), X-Initiative, SEMATECH, RAPID (Reusable Application-Specific Intellectual Property Developers), and VCX (Virtual Component Exchange).

CUSTOMER-DRIVEN FOUNDRY SOLUTIONS

UMC is a leading semiconductor foundry that provides advanced technology and manufacturing services for applications spanning every major sector of the IC industry. UMC's customer-driven foundry solutions enable chip designers to leverage the strength of the company's leading-edge processes, which include production technologies down to 28nm.

Broad Technologies in Multiple Fabs

A broad range of technologies span across UMC's multiple fabs. In addition, UMC's manufacturing expertise and 30 years of manufacturing experience ensure industry-leading turnaround times and defect densities. Comprehensive process control systems with advanced methodologies and a strong engineering team support fast product ramp to reach consistent and stable yields. UMC's Yield Enhancement Vehicle (YEV) in advanced nodes also helps to stabilize yield and accelerate time to market by verifying the process before customer product tape-out.

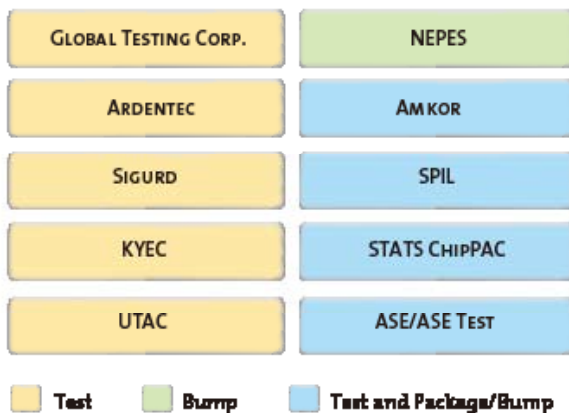


Verified Package Solutions

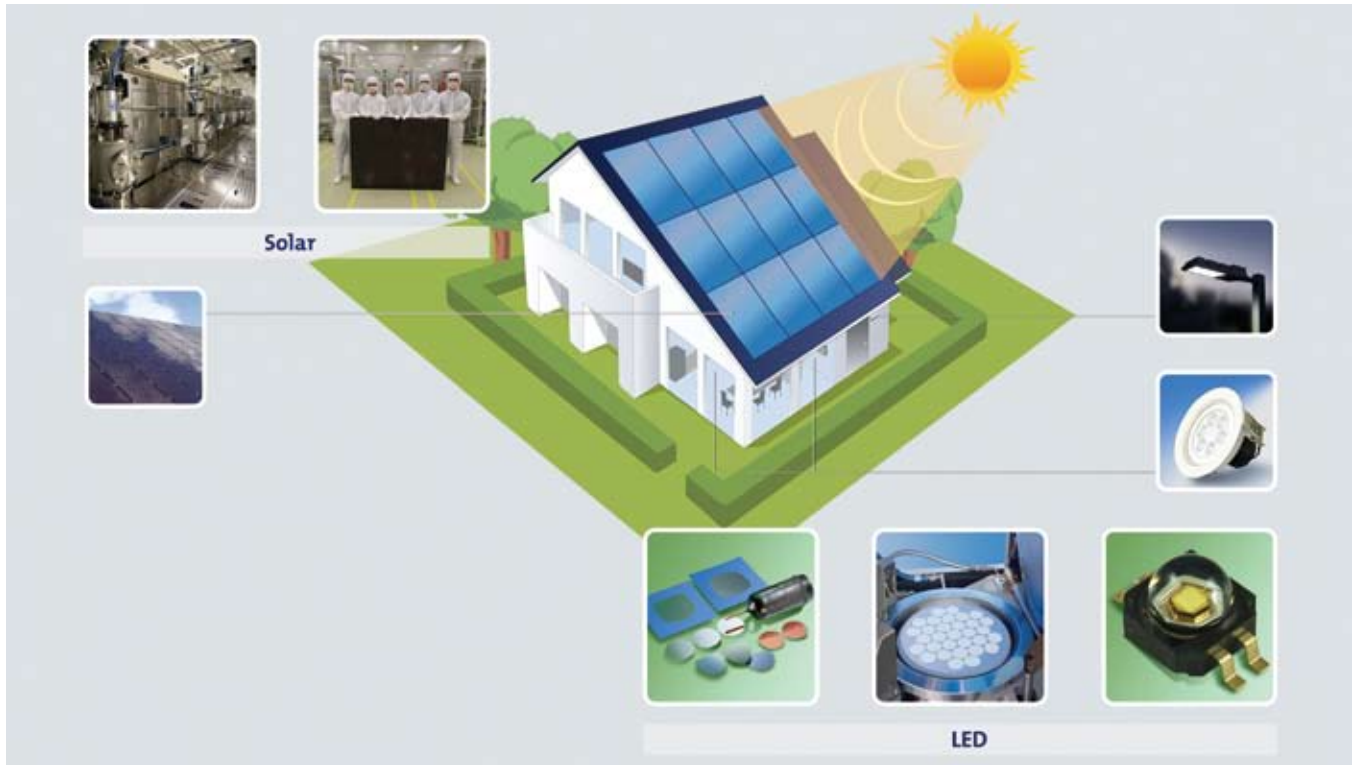
Solutions	Capability
Bump / Flip Chip	Solder: 8" & 12" wafer
	150um solder bump pitch
Wire Bond	45um in-line pad pitch
BOAC	40nm low-k
MCP / SiP	Stacked die, POP & PIP
Lead Free Package	Wire Bond
	Flip Chip

Testing/Package Partners

UMC's major test and package subcontractors are located in Taiwan and throughout Asia. The close proximity of UMC's test and package partners to UMC creates synergies that enable faster service and greater flexibility.



GREEN TECHNOLOGY INVESTMENT



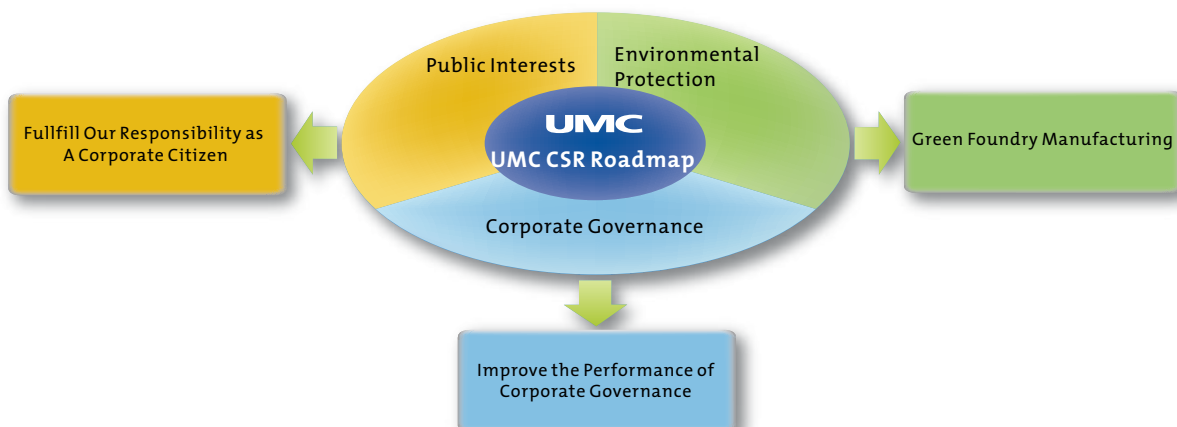
UMC's CSR COMMITMENT

UMC maintains a business philosophy of pursuing sustainable operations while building long-term partnerships with customers and the communities in which it operates. Fulfilling its responsibilities as a corporate citizen and maintaining advanced health, safety and environmental standards have been important policies and commitments for UMC. UMC has been promoting social responsibility for a long time, based on the concept of "caring for employees, environment first and working for the best interest of the public" as a means of giving back to the community.

Inventory and Verification of Carbon Emission

UMC has established a greenhouse gas emission inventory system following the requirement of ISO 14064-1 and Greenhouse Gas Protocol. The GHG emission amount of all UMC fabs since 2000 has been inventoried. In 2009, UMC was first to announce product carbon footprint

verification on integrated circuit wafers. UMC's product carbon footprint inventory was implemented on the basis of the ISO 14040 series and integrated with ISO 14064-1 greenhouse gas emission inventory data to complete eco-profile calculations that were performed on the principles of BSI PAS 2050.



For more Information, please visit www.umc.com or e-mail to sales@umc.com

GLOBAL OPERATIONS

UMC has offices in North America, Europe and throughout Asia to serve its global customers. The company's manufacturing base consists of 10 wafer fabs, including advanced 300mm facilities in both Taiwan and Singapore.



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Fab 12A

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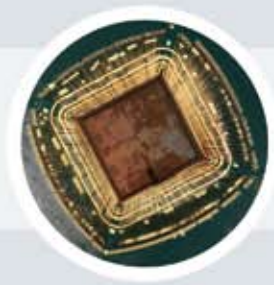
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